

LASER SYSTEM AND METHOD FOR FUNCTIONAL TRIMMING
OF FILMS AND DEVICES

Abstract of the Disclosure

5 A laser system (50) and processing method
exploit a wavelength range (40) in which devices,
including any semiconductor material-based devices (10)
affected by conventional laser wavelengths and devices
having light-sensitive or photo-electronic portions
10 integrated into their circuits, can be effectively
functionally trimmed without inducing performance drift or
malfunctions in the processed devices. True measurement
values of operational parameters of the devices can,
therefore, be obtained without delay for device recovery,
15 i.e., can be obtained substantially instantaneously with
laser impingement. Accordingly, the present invention
allows faster functional laser processing, eases geometric
restrictions on circuit design, and facilitates production
of denser and smaller devices.

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